BS EN IEC 60747-16-6:2019

BSI Standards Publication

Semiconductor devices

Part 16-6: Microwave integrated circuits — Frequency multipliers

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National foreword

This British Standard is the UK implementation of EN IEC 60747-16-6:2019. It is identical to IEC 60747-16-6:2019.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Date	Text affected

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 60747-16-6

August 2019

ICS 31.080.99

English Version

Semiconductor devices - Part 16-6: Microwave integrated circuits - Frequency multipliers (IEC 60747-16-6:2019)

Dispositifs à semiconducteurs - Partie 16-6: Circuits intégrés hyperfréquences - Multiplicateurs de fréquence (IEC 60747-16-6:2019)

Halbleiterbauelemente - Teil 16-6: Integrierte Mikrowellenschaltkreise - Frequenzvervielfachung (IEC 60747-16-6:2019)

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European foreword

The text of document 47E/602/CDV, future edition 1 of IEC 60747-16-6, prepared by SC 47E "Discrete semiconductor devices" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60747-16-6:2019.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2020-04-30
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2022-07-31

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60617	-	Graphical symbols for diagrams	-	-
IEC 60747-1	2006	Semiconductor devices - Part 1: General	-	-
+ A1	2010		-	-
IEC 60747-4	-	Semiconductor devices - Discrete devices - Part 4: Microwave diodes and transistors	-	-
IEC 60747-16-3	2002	Semiconductor devices - Part 16-3: Microwave integrated circuits - Frequency converters	EN 60747-16-3	2002
+ A1	2009		+ A1	2009
+ A2	2017		+ A2	2017
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC/TR 61340-5-2	-	Electrostatics -- Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide	CLC/TR 61340-5-2	-

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SEMICONDUCTOR DEVICES –

Part 16-6: Microwave integrated circuits – Frequency multipliers

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International Standard IEC 60747-16-6 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

CDV	Report on voting
47E/602/CDV	47E/622A/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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A list of all parts in the IEC 60747 series, published under the general title *Semiconductor devices,* can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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